

φ0.090 Ultra Micro-Hole Drilling Performance

φ0.090 ドリル 加工事例

用途: 半導体パッケージ、各種デバイス用基板 等 FBGA、BGA、Device substrate etc...

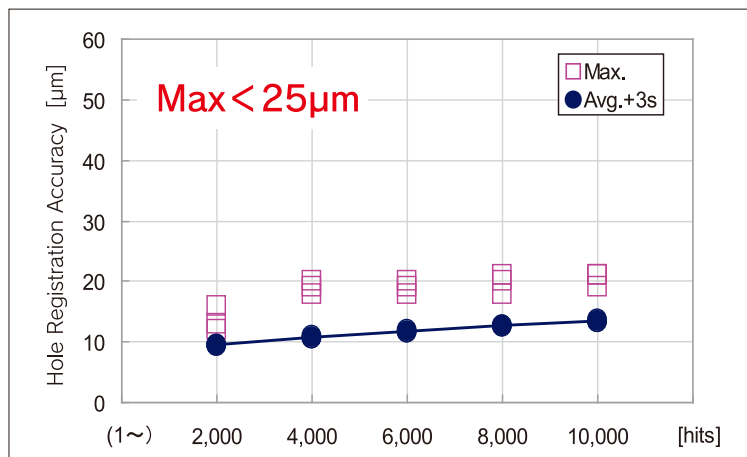
Drilling Condition 加工条件

Work Material : MCL-E-679GT t0.1(Double Sided) x 6 stack height 5/5μmCopper

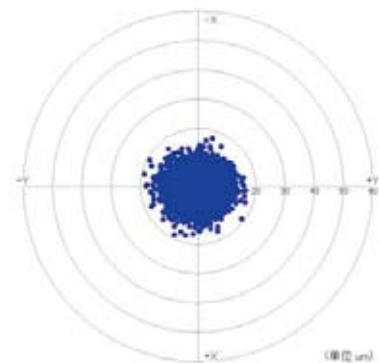
S : 350,000 min⁻¹ F : 1.75 m/min f : 5 μm/rev

Set Life : 10,000 hits

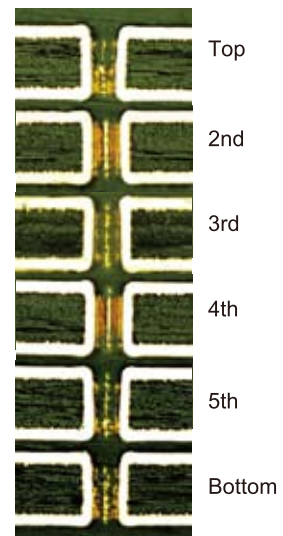
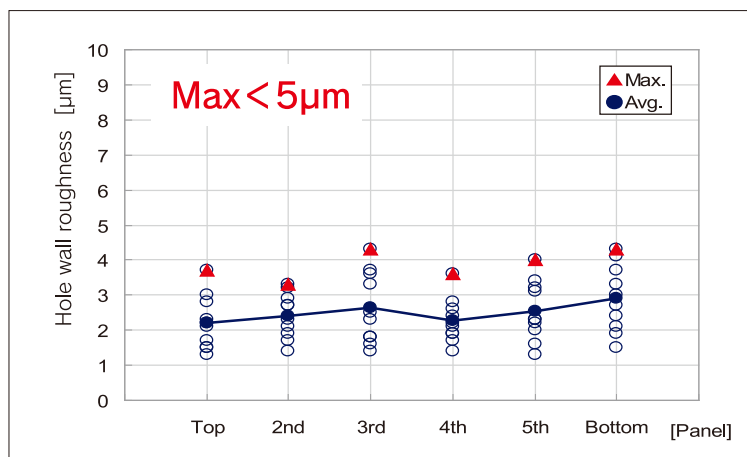
Hole Registration Accuracy 穴位置精度



10,000 hits



Hole Wall Quality at 10,000th hit 内壁粗さ



'08JPCA展示データ
 Work Material : MCL-E-679FG(R)
 t0.1(Double Sided) x 5 stack height (4/4μmCopper)
 Set Life : 10,000hits
 Hole Registration Accuracy : Max<25μm
 Hole Wall Quality at 10,000hits : Max≤3μm

Continuous high quality
 高品質を維持

Coming soon Low-CTE material
 drilling for next generation
 次世代を見据えたLow-CTE材加工